

## Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations Autorisiert durch:

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## Materialien und Stoffe

| Verwendung/Andordnung | Materialgruppe            | % w/w des Materials im Artikel | Substances in the material                  | CAS Number | % w/w des Stoffs im Artikel |
|-----------------------|---------------------------|--------------------------------|---------------------------------------------|------------|-----------------------------|
| Chip (die)            | Other inorganic materials | 11.5%                          | Gold                                        | 7440-57-5  | 8.5%                        |
|                       |                           |                                | ALUMINIUM                                   | 7429-90-5  | 12%                         |
|                       |                           |                                | Silicon                                     | 7440-21-3  | 79.5%                       |
| Die attach            | Gold                      | 3.5%                           | Tin                                         | 7440-31-5  | 20%                         |
|                       |                           |                                | Gold                                        | 7440-57-5  | 80%                         |
| Encapsulation         | EP (Epoxy resin)          | 47.2%                          | Carbon black                                | 1333-86-4  | 0.3%                        |
|                       |                           |                                | Crystallized silicon dioxide                | 14808-60-7 | 0.8%                        |
|                       |                           |                                | 2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane | 1675-54-3  | 0.99%                       |
|                       |                           |                                | Epoxy resin 89                              | 26335-32-0 | 27.61%                      |
|                       |                           |                                | Quartz sand                                 | 60676-86-0 | 70.3%                       |
| Inner preparation     | Gold                      | 1.5%                           | Gold                                        | 7440-57-5  | 100%                        |
| Leadfinish            | Tin plating               | 5.3%                           | Tin                                         | 7440-31-5  | 100%                        |

| Verwendung/Andordnung | Materialgruppe                                  | % w/w des Materials im Artikel | Substances in the material | CAS Number | % w/w des Stoffs im Artikel |
|-----------------------|-------------------------------------------------|--------------------------------|----------------------------|------------|-----------------------------|
| Leadframe             | Copper (e.g. copper amounts in cable harnesses) | 31%                            | Magnesium                  | 7439-95-4  | 0.2%                        |
|                       |                                                 |                                | Nickel                     | 7440-02-0  | 2.8%                        |
|                       |                                                 |                                | Copper                     | 7440-50-8  | 97%                         |

## Beigefügte Artikelliste

| Artikelnummer | Artikelbezeichnung   | Artikelmasse | Artikelmasse UoM |
|---------------|----------------------|--------------|------------------|
| QFN2x2        | Diode/Transistor SMD | 0.05         | g                |